

Data sheet acquired from Harris Semiconductor SCHS212D

February 1998 - Revised October 2003

High-Speed CMOS Logic Quad Analog Switch with Level Translation

Features

- Fast Switching and Propagation Delay Times
- Low "OFF" Leakage Current
- · Built-In "Break-Before-Make" Switching
- Logic-Level Translation to Enable 5V Logic to Accommodate ±5V Analog Signals
- Wide Operating Temperature Range ... -55°C to 125°C
- HC Types
 - 2V to 10V Operation
 - High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC} at V_{CC} = 5V
- HCT Types
 - Direct LSTTL Input Logic Compatibility,
 V_{IL}= 0.8V (Max), V_{IH} = 2V (Min)
 - CMOS Input Compatibility, $I_I \le 1\mu A$ at V_{OL} , V_{OH}

Description

The 'HC4316 and CD74HCT4316 contain four independent digitally controlled analog switches that use silicon-gate CMOS technology to achieve operating speeds similar to LSTTL with the low power consumption of standard CMOS integrated circuits.

In addition these devices contain logic-level translation circuits that provide for analog signal switching of voltages between $\pm 5 \text{V}$ via 5V logic. Each switch is turned on by a high-level voltage on its select input (S) when the common Enable (E) is Low. A High E disables all switches. The digital inputs can swing between VCC and GND; the analog inputs/outputs can swing between VCC as a positive limit and VEE as a negative limit. Voltage ranges are shown in Figures 2 and 3.

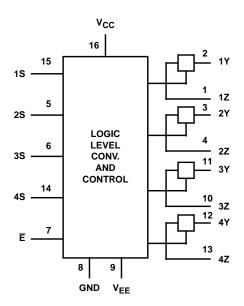
Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC4316F3A	-55 to 125	16 Ld CERDIP
CD74HC4316E	-55 to 125	16 Ld PDIP
CD74HC4316M	-55 to 125	16 Ld SOIC
CD74HC4316MT	-55 to 125	16 Ld SOIC
CD74HC4316M96	-55 to 125	16 Ld SOIC
CD74HC4316NSR	-55 to 125	16 Ld SOP
CD74HC4316PW	-55 to 125	16 Ld TSSOP
CD74HC4316PWR	-55 to 125	16 Ld TSSOP
CD74HC4316PWT	-55 to 125	16 Ld TSSOP
CD74HCT4316E	-55 to 125	16 Ld PDIP
CD74HCT4316M	-55 to 125	16 Ld SOIC
CD74HCT4316MT	-55 to 125	16 Ld SOIC
CD74HCT4316M96	-55 to 125	16 Ld SOIC

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

Pinout CD54HC4316 (CERDIP) CD74HC4316 (PDIP, SOIC, SOP, TSSOP) CD74HCT4316 (PDIP, SOIC) TOP VIEW 16 V_{CC} 1Z 1 15 1S 14 4S 2Y 3 13 4Z 2Z T4 2S 5 12 4Y 11 3Y 3S 6 E 7 10 3Z GND 8 9 V_{EE}

Functional Diagram



TRUTH TABLE

INP	UTS	
Ē	S	SWITCH
L	L	OFF
L	Н	ON
Н	Х	OFF

H= High Level Voltage L= Low Level Voltage

X= Don't Care

Logic Diagram

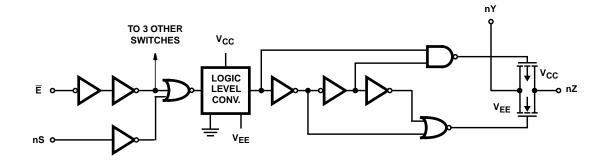


FIGURE 1. ONE SWITCH

Absolute Maximum Ratings

DC Supply Voltage, V _{CC} 0.5V to 7V
DC Supply Voltage, V _{CC} - V _{EE} 0.5V to 10.5V
DC Supply Voltage, V _{EE} 0.5V to -7V
DC Input Diode Current, I _{IK}
For $V_I < -0.5V$ or $V_I > V_{CC} \ 0.5V$ ±20mA
DC Switch Diode Current, IOK
For V _I < V _{EE} -0.5V or V _I < V _{CC} + 0.5V±25mA
DC Switch Diode Current
For $V_I > V_{EE}$ -0.5V or $V_I < V_{CC} + 0.5V$ ±25mA
DC Output Diode Current, IOK
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ ±20mA
DC Output Source or Sink Current per Output Pin, IO
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ ±25mA
DC V _{CC} or Ground Current, I _{CC}

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note 1):
E (PDIP) Package
M (SOIC) Package73°C/W
NS (SOP) Package
PW (TSSOP) Package108°C/W
Maximum Junction Temperature (Plastic Package) 150°
Maximum Storage Temperature Range65°C to 150°
Maximum Lead Temperature (Soldering 10s) 300°
SOIC - Lead Tips Only

Operating Conditions

Temperature Range, T _A 55°C to 125°C	С
Supply Voltage Range, V _{CC}	
HC Types2V to 6'	٧
HCT Types	٧
Supply Voltage Range, V _{CC -} V _{EE}	
HC, HCT Types (Figure 2)2V to 10	٧
Supply Voltage Range, V _{EE}	
HC, HCT Types (Figure 3)	٧
DC Input or Output Voltage, V ₁ GND to V _C	С
Analog Switch I/O Voltage, V _{IS} V _{EE} (Mir	n)
V _{CC} (Max	
Input Rise and Fall Time, t _r , t _f	
2V	x)
4.5V 500ns (Max	x)
6V	
0.4477044.04	

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Area as a Function of Supply Voltage

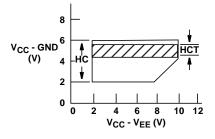


FIGURE 2.

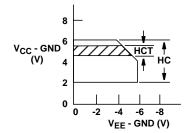


FIGURE 3.

DC Electrical Specifications

			TEST COI	NDITIONS			25°C			C TO OC	-55°C TO 125°C		
PARAMETER	ARAMETER SYMBOL VI		V _I (V) V _{IS} (V)		V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN MAX		UNITS
HC TYPES													
High Level Input	V _{IH}	-	-	-	2	1.5	-	-	1.5	-	1.5	-	V
Voltage					4.5	3.15	-	-	3.15	-	3.15	-	V
					6	4.2	-	-	4.2	-	4.2	-	٧
Low Level Input	V _{IL}	-	-	-	2	-	-	0.5	-	0.5	-	0.5	V
Voltage					4.5	-	-	1.35	-	1.35	-	1.35	V
					6	-	-	1.8	-	1.8	-	1.8	V
"ON" Resistance	R _{ON}	V _{IH} or	V _{CC} or	0	4.5	-	45	180	-	225	-	270	Ω
I _O = 1mA (Figures 4, 5)		V_{IL}	V _{EE}	0	6	-	35	160	-	200	-	240	Ω
				-4.5	4.5	-	30	135	-	170	-	205	Ω
			V _{CC} to	0	4.5	-	85	320	-	400	-	480	Ω
			V _{EE}	0	6	-	55	240	-	300	-	360	Ω
				-4.5	4.5	-	35	170	-	215	-	255	Ω
Maximum "ON"	ΔR _{ON}	-	-	0	4.5	-	10	-	-	-	-	-	Ω
Resistance Between Any Two Channels				0	6	-	8.5	-	-	-	-	-	Ω
,				-4.5	4.5	-	5	-	-	-	-	-	Ω
Switch Off Leakage	I _{IZ}	V _{IH} or	V _{CC} -	0	6	-	-	±0.1	-	±1	-	±1	μΑ
Current		V_{IL}	VEE	-5	5	-	-	±0.1	-	±1	-	±1	μΑ
Control Input Leakage Current	I _{IL}	V _{CC} or GND	-	0	6	-	-	±0.1	-	±1	-	±1	μА
Quiescent Device	Icc	V _{CC} or	When	0	6	-	-	8	-	80	-	160	μΑ
Current I _O = 0		GND	$V_{IS} = V_{EE},$ $V_{OS} = V_{CC}$	-5	5	-	-	16	-	160	-	320	μА
			When V _{IS} =V _{CC} , V _{OS} =V _{EE}										
HCT TYPES													
High Level Input Voltage	V _{IH}	-	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	٧
"ON" Resistance	R _{ON}	V _{IH} or	V _{CC} or	0	4.5	-	45	180	-	225	-	270	Ω
I _O = 1mA (Figures 4, 5)		V_{IL}	V _{EE}	-4.5	4.5	-	30	135	-	170	-	205	Ω
· · · · · · · · · · · · · · · · · · ·			V _{CC} to	0	4.5	-	85	320	-	400	-	480	Ω
			VEE	-4.5	4.5	-	35	170	-	215	-	255	Ω
Maximum "ON"	ΔR _{ON}	-	-	0	4.5	-	10	-	-	-	-	-	Ω
Resistance Between Any Two Channels				-4.5	4.5	-	5	-	-	-	-	-	Ω
Switch Off Leakage	I _{IZ}	V _{IH} or	V _{CC} -	0	6	-	-	±0.1	-	±1	-	±1	μΑ
Current		V_{IL}	VEE	-5	5	-	-	±0.1	-	±1	-	±1	μΑ

DC Electrical Specifications (Continued)

			25°C			-40°C TO 85°C		-55°C TO 125°C					
PARAMETER	SYMBOL	V _I (V)	V _{IS} (V)	V _{EE} (V)	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Control Input Leakage Current	lį	V _{CC} or GND	-	0	5.5	-	-	±0.1	ı	±1	-	±1	μА
Quiescent Device	Icc	Any	When	0	5.5	-	-	8	-	80	-	160	μА
Current I _O = 0		Be- tween V _{CC} and GND	$V_{IS} = V_{EE},$ $V_{OS} =$ $V_{CC},$ $When$ $V_{IS} = V_{CC},$ $V_{OS} = V_{EE}$	-4.5	5.5	-	-	16	-	160	-	320	μА
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI_{CC} (Note 2)	V _{CC} -2.1	-	-	4.5 to 5.5		100	360	ı	450	ı	490	μА

NOTE:

HCT Input Loading Table

INPUT	UNIT LOADS
All	0.5

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Table, e.g., 360 μ A max at 25 o C.

Switching Specifications Input t_r, t_f = 6ns

		TEST	V _{EE}	Vcc		25°C			C TO		C TO 5°C	
PARAMETER	SYMBOL	CONDITIONS	(V)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES												
Propagation Delay,	t _{PLH} , t _{PHL}	C _L = 50pF	0	2	-	-	60	-	75	-	90	ns
Switch In to Out			0	4.5	-	-	12	1	15	-	18	ns
			0	6	-	-	10	-	13	-	15	ns
			-4.5	4.5	-	-	8	-	10	-	12	ns
Turn "ON" Time E to Out	t _{PZH} , t _{PZL}	C _L = 50pF	0	2	-	-	205	-	255	-	310	ns
			0	4.5	-	-	41	-	51	-	62	ns
			0	6	-	-	35	-	43	-	53	ns
			-4.5	4.5	-	-	37	-	47	-	56	ns
		C _L = 15pF	-	5	-	17	-	-	-	-	-	ns
Turn "ON" Time nS to Out	t _{PZH} , t _{PZL}	C _L = 50pF	0	2	-	-	175	-	220	-	265	ns
			0	4.5	-	-	35	-	44	-	53	ns
			0	6	-	-	30	-	37	-	45	ns
			-4.5	4.5	-	-	34	-	43	-	51	ns
		C _L = 15pF	-	5	-	14	-	-	-	-	-	ns
Turn "OFF" Time E to Out	t _{PLZ} , t _{PHZ}	C _L = 50pF	0	2	-	-	205	-	255	-	310	ns
			0	4.5	-	-	41	-	51	-	62	ns
			0	6	-	-	35	-	43	-	53	ns
			-4.5	4.5	-	-	37	-	47	-	56	ns
		C _L = 15pF	-	5	-	17	-	-	-	-	-	ns

^{2.} For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

Switching Specifications Input t_r , t_f = 6ns (Continued)

		TEST	V _{EE}	v _{cc}		25°C			C TO °C		C TO 5°C	
PARAMETER	SYMBOL	CONDITIONS	(V)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Turn "OFF" Time nS to Out	t _{PLZ} , t _{PHZ}	C _L = 50pF	0	2	-	-	175	-	220	-	265	ns
			0	4.5	-	-	35	-	44	-	53	ns
			0	6	-	-	30	-	37	-	45	ns
			-4.5	4.5	-	-	34	ı	43	-	51	ns
		C _L = 15pF	-	5	-	14	-	-	-	-	-	ns
Input (Control) Capacitance	C _I	-	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C _{PD}	-	-	5	-	42	-	-	-	-	-	pF
HCT TYPES												
Propagation Delay,	t _{PLH} , t _{PHL}	C _L = 50pF	0	4.5	-	-	12	-	15	-	18	ns
Switch In to Switch Out			-4.5	4.5	-	-	8	-	10	-	12	ns
Turn "ON" Time E to Out	t _{PZH}	C _L = 50pF	0	4.5	-	-	44	-	55	-	66	ns
			-4.5	4.5	-	-	42	-	53	-	63	ns
		C _L = 15pF	-	5	-	18	-	-	-	-	-	ns
	t _{PZL}	C _L = 50pF	0	4.5	-	-	56	-	70	-	85	ns
			-4.5	4.5	-	-	42	-	53	-	63	ns
		C _L = 15pF	-	5	-	24	-	-	-	-	-	ns
Turn "ON" Time nS to Out	t _{PZH}	C _L = 50pF	0	4.5	-	-	40	1	53	1	60	ns
			-4.5	4.5	-	-	34	ı	43	ı	51	ns
		C _L = 15pF	-	5	-	17	-	-	-	-	-	ns
	t _{PZL}	C _L = 50pF	0	4.5	-	-	50	-	63	·	75	ns
			-4.5	4.5	-	-	34	-	43	-	51	ns
		C _L = 15pF	-	5	-	18	-	-	-	-	-	ns
Turn "OFF" Time E to Out	t _{PLZ}	$C_L = 50pF$	0	4.5	-	-	50	-	63	-	75	ns
			-4.5	4.5	-	-	46	-	58	-	69	ns
	t _{PLZ} , t _{PHZ}	C _L = 15pF	-	5	-	21	-	-	-	-	-	ns
Turn "OFF" Time nS to Out	t _{PHZ}	C _L = 50pF	0	4.5	-	-	44	-	55	-	66	ns
			-4.5	4.5	-	-	40	-	50	-	60	ns
	t _{PLZ} , t _{PHZ}	C _L = 15pF	-	5	-	18	-	-	-	-	-	ns
Input (Control) Capacitance	Cl	-	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C _{PD}	-	-	5	-	47	-	-	-	-	-	pF

NOTES:

- 3. $\ensuremath{\text{C}_{\text{PD}}}$ is used to determine the dynamic power consumption, per package.
- 4. $P_D = C_{PD} \ V_{CC}^2 \ f_i + \Sigma \ (C_L + C_S) \ V_{CC}^2 \ f_o$ where f_i = input frequency, f_o = output frequency, C_L = output load capacitance, C_S = switch capacitance, V_{CC} = supply voltage.

Analog Channel Specifications $T_A = 25^{\circ}C$

PARAMETER	TEST CONDITIONS	V _{CC} (V)	HC4316	CD74HCT4316	UNITS
Switch Frequency Response Bandwidth at -3dB (Figure 6)	Figure 9 (Notes 5, 6)	4.5	>200	>200	MHz
Crosstalk Between Any Two Switches (Figure 7)	Figure 8 (Notes 6, 7)	4.5	TBE	TBE	dB

Analog Channel Specifications $T_A = 25^{\circ}C$ (Continued)

PARAMETER	TEST CONDITIONS	V _{CC} (V)	HC4316	CD74HCT4316	UNITS
Total Harmonic Distortion	1kHz, V _{IS} = 4V _{P-P} (Figure 10)	4.5	0.078	0.078	%
	1kHz, V _{IS} = 8V _{P-P} (Figure 10)	9	0.018	0.018	%
Control to Switch Feedthrough Noise	Figure 11	4.5	TBE	TBE	mV
		9	TBE	TBE	mV
Switch "OFF" Signal Feedthrough (Figure 7)	Figure 12 (Notes 6, 7)	4.5	-62	-62	dB
Switch Input Capacitance, C _S	-	-	5	5	pF

NOTES:

- 5. Adjust input level for 0dBm at output, f = 1MHz.
- 6. V_{IS} is centered at $V_{CC}/2$.
- 7. Adjust input for 0dBm at V_{IS} .

Typical Performance Curves

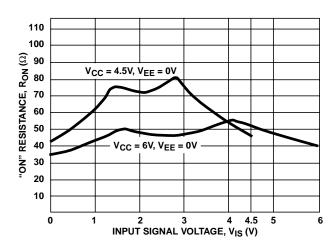


FIGURE 4. TYPICAL "ON" RESISTANCE vs INPUT SIGNAL VOLTAGE

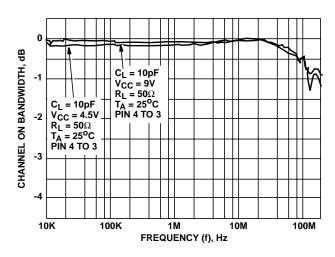


FIGURE 6. SWITCH FREQUENCY RESPONSE

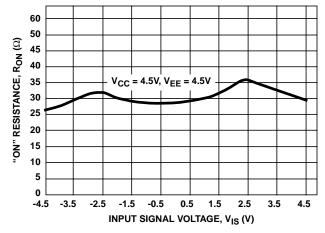


FIGURE 5. TYPICAL "ON" RESISTANCE vs INPUT SIGNAL VOLTAGE

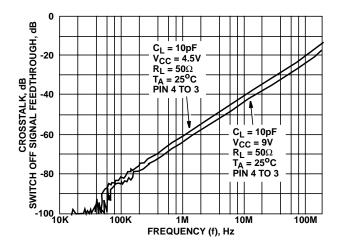
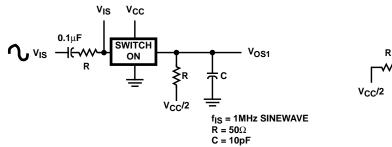


FIGURE 7. SWITCH-OFF SIGNAL FEEDTHROUGH AND CROSSTALK vs FREQUENCY

Analog Test Circuits



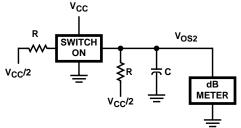


FIGURE 8. CROSSTALK BETWEEN TWO SWITCHES TEST CIRCUIT

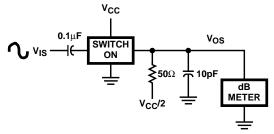


FIGURE 9. FREQUENCY RESPONSE TEST CIRCUIT

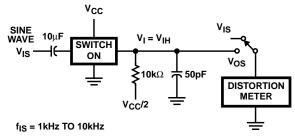


FIGURE 10. TOTAL HARMONIC DISTORTION TEST CIRCUIT

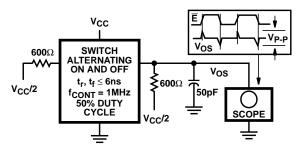


FIGURE 11. CONTROL-TO-SWITCH FEEDTHROUGH NOISE TEST CIRCUIT

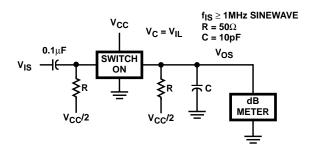


FIGURE 12. SWITCH OFF SIGNAL FEEDTHROUGH

Test Circuits and Waveforms

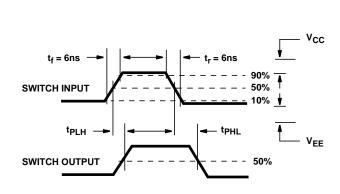


FIGURE 13. SWITCH PROPAGATION DELAY TIMES

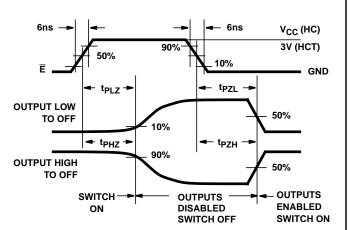
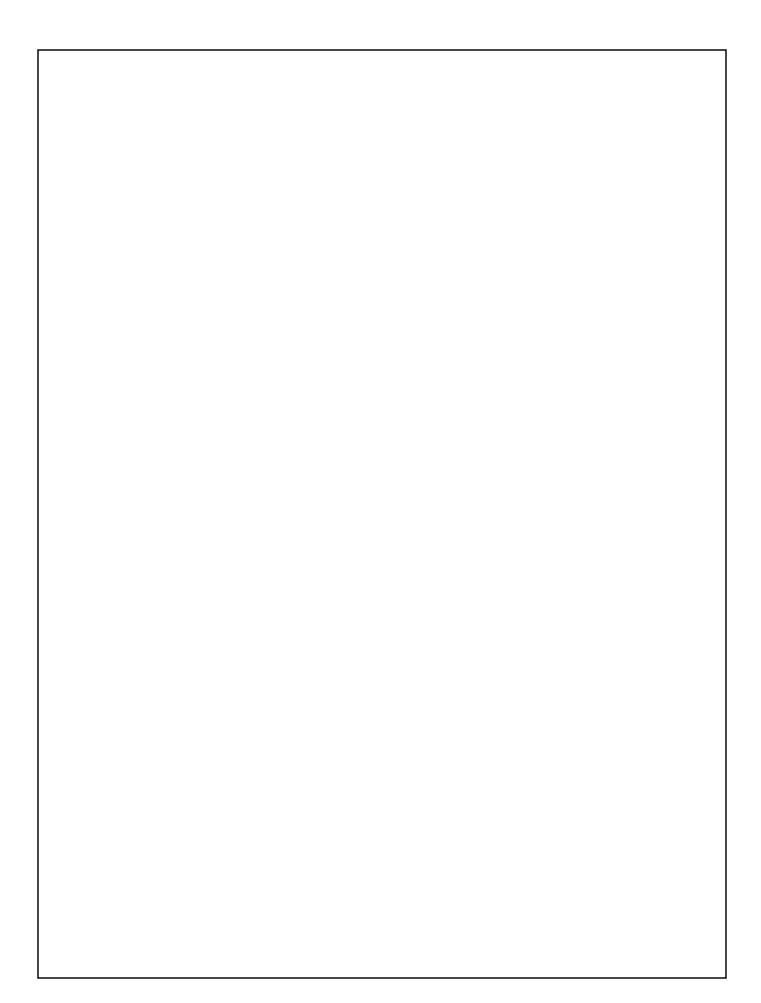


FIGURE 14. SWITCH TURN-ON AND TURN-OFF PROPAGATION DELAY TIMES WAVEFORMS



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

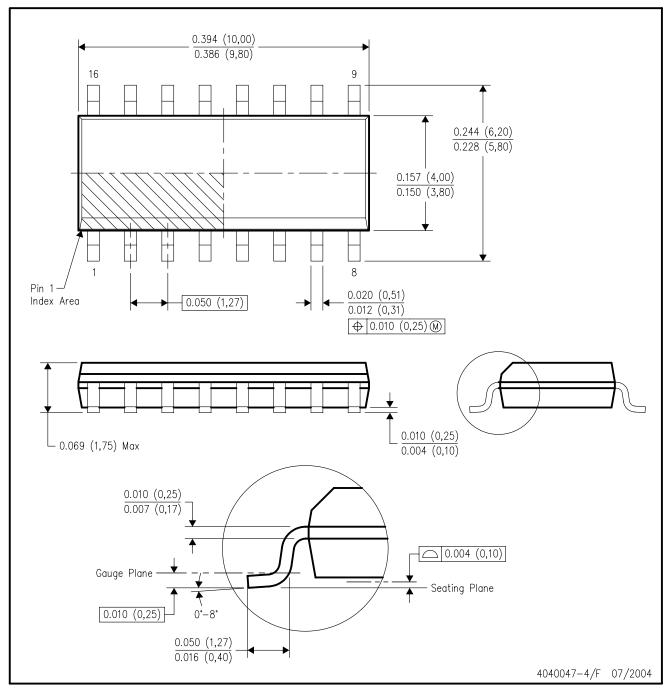


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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